19-0882; Rev 0; 7/07

MAXIM

Low-Power Battery Backup Circuits in Small µDFN Packages

General Description

The MAX16033–MAX16040 supervisory circuits reduce the complexity and number of components required for power-supply monitoring and battery control functions in microprocessor (µP) systems. The devices significantly improve system reliability and accuracy compared to other ICs or discrete components. The MAX16033–MAX16040 provide µP reset, backup-battery switchover, power-fail warning, watchdog, and chip-enable gating features.

The MAX16033–MAX16040 operate from supply voltages up to 5.5V. The factory-set reset threshold voltage ranges from 2.32V to 4.63V. The devices feature a manual-reset input (MAX16033/MAX16037), a watchdog timer input (MAX16034/MAX16038), a battery-on output (MAX16035/MAX16039), an auxiliary adjustable reset input (MAX16036/MAX16040), and chip-enable gating (MAX16033–MAX16036). Each device includes a power-fail comparator and offers an active-low push-pull reset or an active-low open-drain reset.

The MAX16033–MAX16040 are available in 2mm x 2mm, 8-pin or 10-pin µDFN packages and are fully specified from -40°C to +85°C.

Applications

- Portable/Battery-Powered Equipment
- POS Equipment
- Critical µP/µC Power Monitoring
- Set-Top Boxes
- Controllers
- Computers
- Fax Machines
- Industrial Control
- Real-Time Clocks
- Intelligent Instrument

Pin Configurations and Typical Operating Circuit appear at end of data sheet.

Features

- ♦ **Low 1.2V Operating Supply Voltage**
- ♦ **Precision Monitoring of 5.0V, 3.3V, 3.0V, and 2.5V Power-Supply Voltages**
- ♦ **Independent Power-Fail Comparator**
- ♦ **Debounced Manual-Reset Input**
- ♦ **Watchdog Timer, 1.6s Timeout**
- ♦ **Battery-On Output Indicator**
- ♦ **Auxiliary User-Adjustable RESETIN**
- ♦ **Low 13µA Quiescent Supply Current**
- ♦ **Two Available Output Structures:**
  Active-Low Push-Pull Reset
  Active-Low Open-Drain Reset
- ♦ **Active-Low Reset Valid Down to 1.2V**
- ♦ **Power-Supply Transient Immunity**
- ♦ **140ms (min) Reset Timeout Period**
- ♦ **Small 2mm x 2mm, 8-Pin and 10-Pin µDFN Packages**

Ordering Information

PART*	TEMP RANGE	PIN-PACKAGE	PKG CODE
MAX16033LLB_ _+T	-40°C to +85°C	10 µDFN-10	L1022-1
MAX16033PLB_ _+T	-40°C to +85°C	10 µDFN-10	L1022-1
MAX16034LLB_ _+T	-40°C to +85°C	10 µDFN-10	L1022-1
MAX16034PLB_ _+T	-40°C to +85°C	10 µDFN-10	L1022-1

Ordering Information continued on last page.

**These parts offer a choice of reset threshold voltages. From the Reset Threshold Ranges table, insert the desired threshold voltage code in the blank to complete the part number. See Selector Guide for a listing of device features.*

+Denotes a lead-free package.

T = Tape and reel.

Selector Guide

PART	$\overline{MR}$	WATCHDOG	BATTON	RESETIN	$\overline{CEIN}$/$\overline{CEOUT}$	PFI, $\overline{PFO}$	PIN-PACKAGE
MAX16033_	✓				✓	✓	10 µDFN-10
MAX16034_		✓			✓	✓	10 µDFN-10
MAX16035_			✓		✓	✓	10 µDFN-10
MAX16036_				✓	✓	✓	10 µDFN-10
MAX16037_	✓					✓	8 µDFN-8
MAX16038_		✓				✓	8 µDFN-8
MAX16039_			✓			✓	8 µDFN-8
MAX16040_				✓		✓	8 µDFN-8

Note: *Replace "_" with L for push-pull or P for open-drain $\overline{RESET}$ and $\overline{PFO}$ outputs.*

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

Low-Power Battery Backup Circuits in Small µDFN Packages

ABSOLUTE MAXIMUM RATINGS

Terminal Voltages (with respect to GND)
V_{CC}, BATT, OUT .....-0.3V to +6V
$\overline{RESET}$ (open drain), $\overline{PFO}$ (open drain) .....-0.3V to +6V
$\overline{RESET}$ (push-pull), $\overline{PFO}$ (push-pull), BATTON, RESETIN, WDI
$\overline{MR}$, $\overline{CEIN}$, $\overline{CEOUT}$, PFI .....-0.3V to (V_{OUT} + 0.3V)
Input Current
V_{CC} Peak.....1A
V_{CC} Continuous 250mA
BATT Peak 250mA
BATT Continuous 40mA
GND 75mA

Output Current
$\overline{OUT}$ .....Short-Circuit Protected for up to 5s
$\overline{RESET}$, BATTON 20mA
Continuous Power Dissipation (T_A = +70°C)
8-Pin µDFN (derate 4.8mW/°C above +70°C) 380.6mW
10-Pin µDFN (derate 5mW/°C above +70°C) 402.8mW
Operating Temperature Range .....-40°C to +85°C
Storage Temperature Range .....-65°C to +150°C
Lead Temperature (soldering, 10s) .....+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

(V_{CC} = 2.25V to 5.5V, V_{BATT} = 3V, $\overline{RESET}$ not asserted, T_A = -40°C to +85°C, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Operating Voltage Range	V_{CC}, V_{BATT}	No load (Note 2)		0		5.5	V
Supply Current	I_{CC}	No load, $V_{CC} > V_{TH}$	V_{CC} = 2.8V		13	30	µA
			V_{CC} = 3.6V		16	35	
			V_{CC} = 5.5V		22	50	
Supply Current in Battery Backup Mode		V_{BATT} = 2.8V, V_{CC} = 0V, excluding I_{OUT}	T_A = +25°C			1	µA
			T_A = -40°C to +85°C			2	
BATT Standby Current (Note 3)	I_{BATT}	(V_{BATT} + 0.2V) < V_{CC} < 5.5V	T_A = +25°C	-0.1		+0.02	µA
			T_A = -40°C to +85°C	-0.3		+0.02	
V_{CC} to OUT On-Resistance	R_{ON}	V_{CC} = 4.75V, $V_{CC} > V_{TH}$, I_{OUT} = 150mA				3.1	Ω
		V_{CC} = 3.15V, $V_{CC} > V_{TH}$, I_{OUT} = 65mA				3.7	
		V_{CC} = 2.5V, $V_{CC} > V_{TH}$, I_{OUT} = 25mA				4.6	
Output Voltage in Battery Backup Mode	V_{OUT}	V_{BATT} = 4.50V, V_{CC} = 0V, I_{OUT} = 20mA		V_{BATT} - 0.2			V
		V_{BATT} = 3.15V, V_{CC} = 0V, I_{OUT} = 10mA		V_{BATT} - 0.15			
		V_{BATT} = 2.5V, V_{CC} = 0V, I_{OUT} = 5mA		V_{BATT} - 0.15			
Battery-Switchover Threshold	V_{SW}	V_{CC} - V_{BATT}, $V_{CC} < V_{TH}$	V_{CC} rising	0			mV
			V_{CC} falling	-40			

ELECTRICAL CHARACTERISTICS (continued)

(V_{CC} = 2.25V to 5.5V, V_{BATT} = 3V, $\overline{RESET}$ not asserted, T_A = -40°C to +85°C, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
RESET OUTPUT							
Reset Threshold	V_{TH}	MAX160_ _ _L_46		4.50	4.63	4.75	V
		MAX160_ _ _L_44		4.25	4.38	4.50	
		MAX160_ _ _L_31		3.00	3.08	3.15	
		MAX160_ _ _L_29		2.85	2.93	3.00	
		MAX160_ _ _L_26		2.55	2.63	2.70	
		MAX160_ _ _L_23		2.25	2.32	2.38	
V_{CC} Falling Reset Delay		V_{CC} falling at 10V/ms			25		µs
Reset Active Timeout Period	t_{RP}			140		280	ms
$\overline{RESET}$ Output Low Voltage	V_{OL}	$\overline{RESET}$ asserted	I_{SINK} = 1.6mA, $V_{CC} \geq$ 2.1V			0.3	V
			I_{SINK} = 100µA, $V_{CC} \geq$ 1.2V			0.4	
$\overline{RESET}$ Output High Voltage	V_{OH}	MAX160_ _L only (push-pull), $\overline{RESET}$ not asserted, I_{SOURCE} = 500µA, $V_{CC} \geq V_{TH(MAX)}$		0.8 x V_{CC}			V
$\overline{RESET}$ Output Leakage Current	I_{LKG}	MAX160_ _P only (open drain), not asserted				1	µA
POWER-FAIL COMPARATOR							
PFI Input Threshold	V_{PFI}	V_{PFI} falling		1.185	1.235	1.285	V
PFI Hysteresis					1		%
PFI Input Current		V_{PFI} = 0V or V_{CC}		-100		+100	nA
$\overline{PFO}$ Output Low Voltage	V_{OL}	Output asserted	$V_{CC} \geq$ 2.1V, I_{SINK} = 1.6mA			0.3	V
			$V_{CC} \geq$ 1.2V, I_{SINK} = 100µA			0.4	
$\overline{PFO}$ Output High Voltage	V_{OH}	MAX160_ _L only (push-pull), $V_{CC} \geq V_{TH(MAX)}$, I_{SOURCE} = 500µA, output not asserted		0.8 x V_{CC}			V
$\overline{PFO}$ Leakage Current		MAX160_ _P only (open drain), V_{PFO} = 5.5V, not asserted				1	µA
$\overline{PFO}$ Delay Time		V_{PFI} + 100mV to V_{PFI} - 100mV			4		µs
MANUAL RESET (MAX16033/MAX16037)							
$\overline{MR}$ Input Voltage	V_{IL}					0.3 x V_{CC}	V
	V_{IH}			0.7 x V_{CC}			
Pullup Resistance to V_{CC}				20		165	kΩ
Minimum Pulse Width				1			µs
Glitch Immunity		V_{CC} = 3.3V			100		ns
$\overline{MR}$ to Reset Delay					120		ns

Low-Power Battery Backup Circuits in Small µDFN Packages

ELECTRICAL CHARACTERISTICS (continued)

(V_{CC} = 2.25V to 5.5V, V_{BATT} = 3V, $\overline{RESET}$ not asserted, T_A = -40°C to +85°C, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

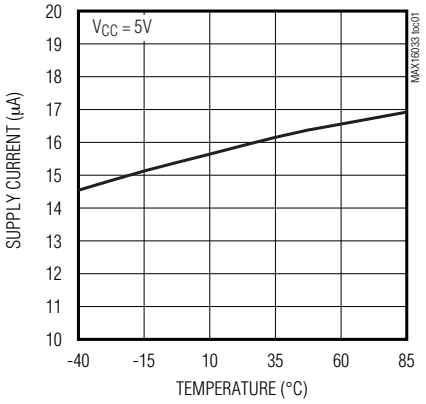
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
WATCHDOG (MAX16034/MAX16038)						
Watchdog Timeout Period	t_{WD}		1.00	1.65	2.25	s
Minimum WDI Input Pulse Width	t_{WDI}	(Note 4)	100			ns
WDI Input Voltage	V_{IL}				0.3 x V_{CC}	V
	V_{IH}		0.7 x V_{CC}			
WDI Input Current			-1.0		+1.0	µA
BATTON (MAX16035/MAX16039)						
Output Voltage	V_{OL}	I_{SINK} = 3.2mA, V_{BATT} = 2.1V			0.4	V
Output Short-Circuit Current		Sink current, V_{CC} = 5V		60		mA
		Source current, $V_{BATT} \geq$ 2V	10	30	120	µA
RESETIN (MAX16036/MAX16040)						
RESETIN Threshold	V_{RTH}		1.185	1.235	1.285	V
RESETIN Input Current				0.01	25	nA
RESETIN to Reset Delay		(V_{RTH} + 100mV) to (V_{RTH} - 100mV)		1.5		µs
CHIP-ENABLE GATING (MAX16033–MAX16036)						
$\overline{CE}$IN Leakage Current		$\overline{RESET}$ asserted			±1	µA
$\overline{CE}$IN to $\overline{CE}$OUT Resistance		$\overline{RESET}$ not asserted, $V_{CC} = V_{TH(MAX)}$, $V_{\overline{CE}IN} = V_{CC} / 2$, I_{SINK} = 10mA			100	Ω
$\overline{CE}$OUT Short-Circuit Current		$\overline{RESET}$ asserted, $V_{\overline{CE}OUT}$ = 0V		1	2.0	mA
$\overline{CE}$IN to $\overline{CE}$OUT Propagation Delay (Note 4)		50Ω source impedance driver, C_{LOAD} = 50pF, V_{CC} = 4.75V		1.5	7	ns
		50Ω source impedance driver, C_{LOAD} = 50pF, V_{CC} = 3.15V		2	9	
$\overline{CE}$OUT Output-Voltage High		V_{CC} = 5V, $V_{CC} \geq V_{BATT}$, I_{SOURCE} = 100µA	0.7 x V_{CC}			V
		V_{CC} = 0V, $V_{BATT} \geq$ 2.2V, I_{SOURCE} = 1µA	V_{BATT} - 0.1			
$\overline{RESET}$ to $\overline{CE}$OUT Delay				1		µs

Note 1: All devices are 100% production tested at T_A = +25°C. All overtemperature limits are guaranteed by design.
Note 2: V_{BATT} can be 0V any time, or V_{CC} can go down to 0V if V_{BATT} is active (except at startup).
Note 3: Positive current flows into BATT.
Note 4: Guaranteed by design.

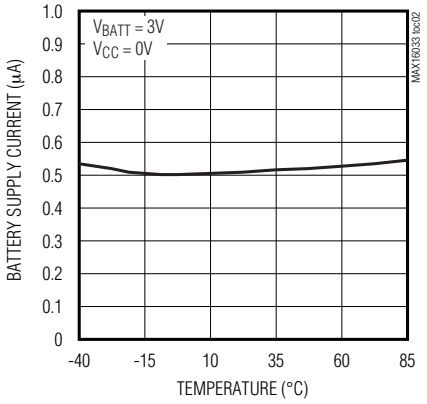
Typical Operating Characteristics

(T_A = +25°C, unless otherwise noted.)

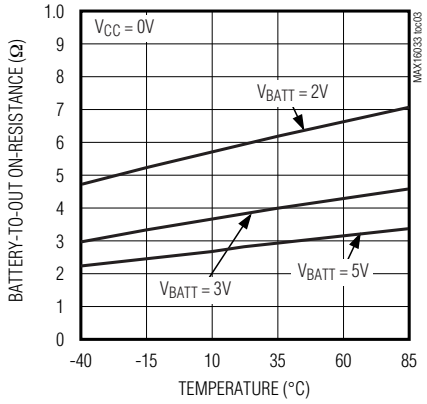
SUPPLY CURRENT vs. TEMPERATURE



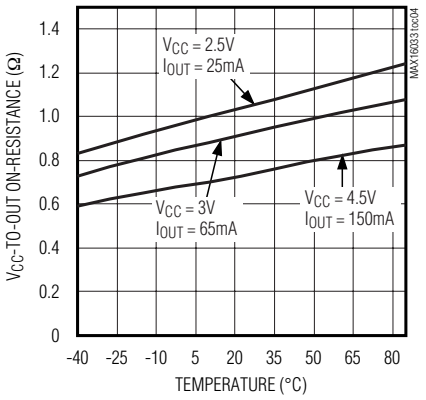
BATTERY SUPPLY CURRENT (BACKUP MODE) vs. TEMPERATURE



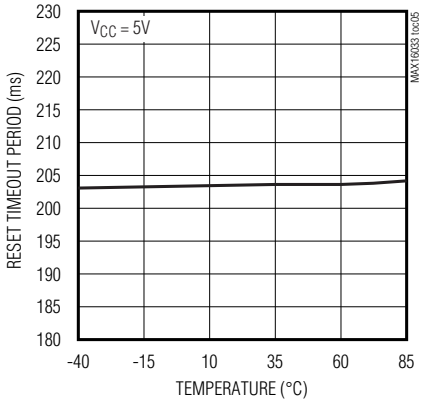
BATT-TO-OUT ON-RESISTANCE vs. TEMPERATURE



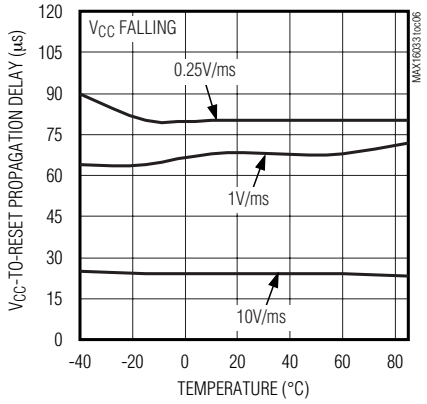
VCC-TO-OUT ON-RESISTANCE vs. TEMPERATURE



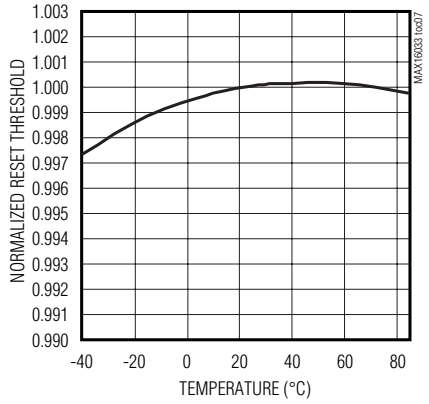
RESET TIMEOUT PERIOD vs. TEMPERATURE



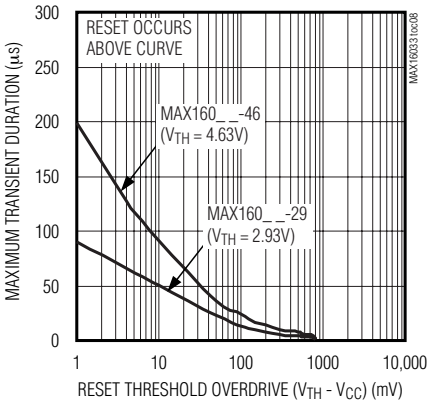
VCC-TO-RESET PROPAGATION DELAY vs. TEMPERATURE



NORMALIZED RESET THRESHOLD vs. TEMPERATURE



MAXIMUM TRANSIENT DURATION vs. RESET THRESHOLD OVERDRIVE

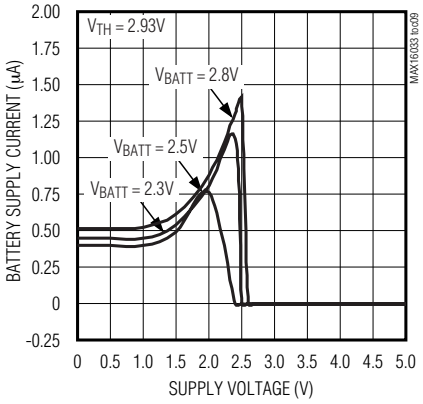


Low-Power Battery Backup Circuits in Small µDFN Packages

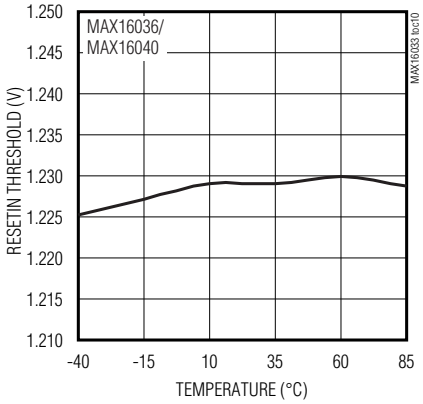
Typical Operating Characteristics (continued)

(T_A = +25°C, unless otherwise noted.)

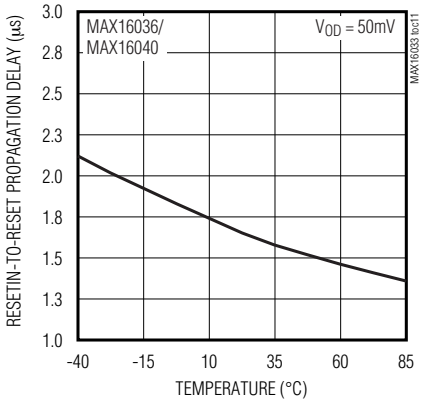
BATTERY SUPPLY CURRENT vs. SUPPLY VOLTAGE



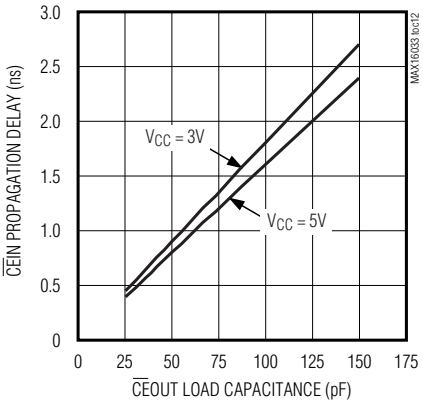
RESETIN THRESHOLD vs. TEMPERATURE



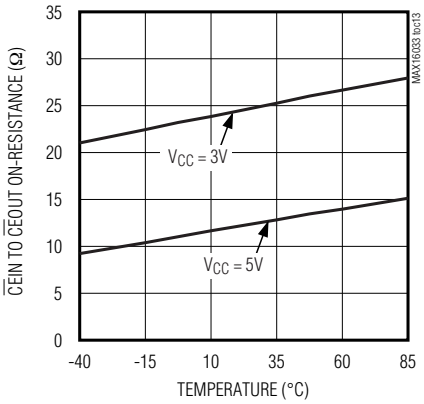
RESETIN-TO-RESET PROPAGATION DELAY vs. TEMPERATURE



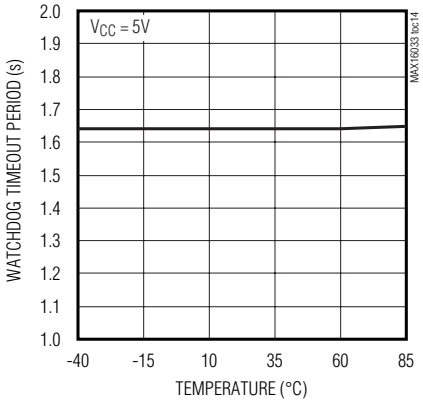
$\overline{CEIN}$ PROPAGATION DELAY vs. $\overline{CEOUT}$ LOAD CAPACITANCE



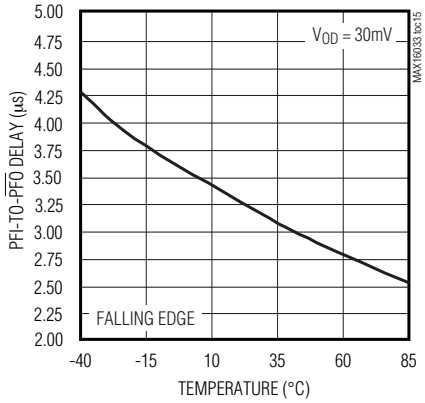
$\overline{CEIN}$ TO $\overline{CEOUT}$ ON-RESISTANCE vs. TEMPERATURE



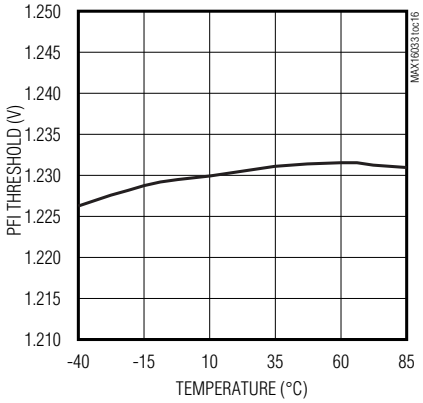
WATCHDOG TIMEOUT PERIOD vs. TEMPERATURE



PFI-TO-$\overline{PFO}$ DELAY vs. TEMPERATURE



PFI THRESHOLD vs. TEMPERATURE

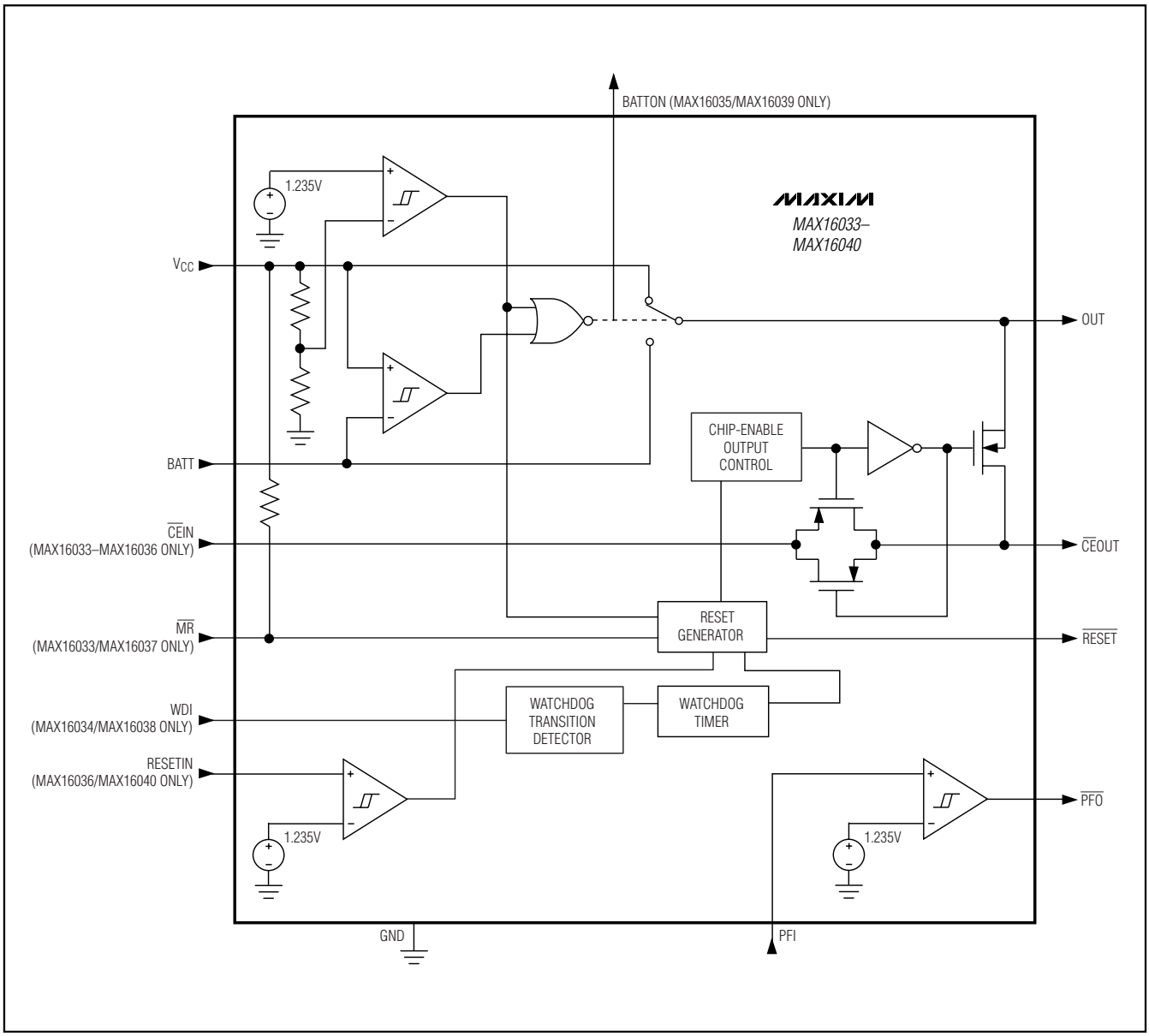


Pin Description

PIN		NAME	FUNCTION
MAX16033–MAX16036 (10-pin µDFN)	MAX16037–MAX16040 (8-pin µDFN)		
1	1	$\overline{RESET}$	Active-Low Reset Output. $\overline{RESET}$ remains low when V_{CC} is below the reset threshold (V_{TH}), the manual-reset input is low, or RESETIN is low. It asserts low in pulses when the internal watchdog times out. $\overline{RESET}$ remains low for the reset timeout period (t_{RP}) after V_{CC} rises above the reset threshold, after the manual-reset input goes from low to high, after RESETIN goes high, or after the watchdog triggers a reset event. The MAX160_ _L is an active-low push-pull output, while the MAX160_ _P is an active-low open-drain output.
2	—	$\overline{CEIN}$	Chip-Enable Input. The input to the chip-enable gating circuit. Connect to GND or OUT if not used.
3	2	PFI	Power-Fail Input. $\overline{PFO}$ goes low when V_{PFI} falls below 1.235V.
4	3	GND	Ground
5	4	$\overline{MR}$	Manual-Reset Input (MAX16033/MAX16037). Driving $\overline{MR}$ low asserts $\overline{RESET}$. $\overline{RESET}$ remains asserted as long as $\overline{MR}$ is low and for the reset timeout period (t_{RP}) after $\overline{MR}$ transitions from low to high. Leave unconnected, or connect to V_{CC} if not used. $\overline{MR}$ has an internal 20kΩ pullup to V_{CC}.
		WDI	Watchdog Input (MAX16034/MAX16038). If WDI remains high or low for longer than the watchdog timeout period (t_{WD}), the internal watchdog timer runs out and a reset pulse is triggered for the reset timeout period (t_{RP}). The internal watchdog clears whenever $\overline{RESET}$ asserts or whenever WDI sees a rising or falling edge (Figure 2).
		BATTON	Battery-On Output (MAX16035/MAX16039). BATTON goes high during battery backup mode.
		RESETIN	Reset Input (MAX16036/MAX16040). When RESETIN falls below 1.235V, $\overline{RESET}$ asserts. $\overline{RESET}$ remains asserted as long as RESETIN is low and for at least t_{RP} after RESETIN goes high.
6	5	$\overline{PFO}$	Active-Low Power-Fail Output. $\overline{PFO}$ goes low when V_{PFI} falls below 1.235V. $\overline{PFO}$ stays low until V_{PFI} goes above 1.235V. $\overline{PFO}$ also goes low when V_{CC} falls below the reset threshold voltage.
7	6	V_{CC}	Supply Voltage, 1.2V to 5.5V
8	7	OUT	Output. OUT sources from V_{CC} when $\overline{RESET}$ is not asserted and from the greater of V_{CC} or BATT when V_{CC} is below the reset threshold voltage.
9	8	BATT	Backup Battery Input. When V_{CC} falls below the reset threshold, OUT switches to BATT if V_{BATT} is 40mV greater than V_{CC}. When V_{CC} rises above V_{BATT}, OUT switches to V_{CC}. The 40mV hysteresis prevents repeated switching if V_{CC} falls slowly.
10	—	$\overline{CEOUT}$	Chip-Enable Output. $\overline{CEOUT}$ goes low only when $\overline{CEIN}$ is low and reset is not asserted. When $\overline{CEOUT}$ is disconnected from $\overline{CEIN}$, $\overline{CEOUT}$ is actively pulled up to OUT.

Low-Power Battery Backup Circuits in Small µDFN Packages

Functional Diagram



Detailed Description

The *Typical Operating Circuit* shows a typical connection for the MAX16033–MAX16040. OUT powers the static random-access memory (SRAM). If V_{CC} is greater than the reset threshold (V_{TH}), or if V_{CC} is lower than V_{TH} but higher than V_{BATT}, V_{CC} is connected to OUT. If V_{CC} is lower than V_{TH} and V_{CC} is less than V_{BATT}, BATT is connected to OUT. OUT supplies up to 200mA from V_{CC}. In battery-backup mode, an internal MOSFET connects the backup battery to OUT. The on-resistance of the MOSFET is a function of the backup-battery voltage and temperature and is shown in the BATT-to-OUT On-Resistance vs. Temperature graph in the *Typical Operating Characteristics*.

Chip-Enable Signal Gating (MAX16033–MAX16036 Only)

The MAX16033–MAX16036 provide internal gating of chip-enable ($\overline{CE}$) signals to prevent erroneous data from being written to CMOS RAM in the event of a power failure or brownout condition. During normal operation, the $\overline{CE}$ gate is enabled and passes all $\overline{CE}$ transitions. When reset asserts, this path becomes disabled, preventing erroneous data from corrupting the CMOS RAM. The MAX16033–MAX16036 provide a series transmission gate from $\overline{CE}$IN to $\overline{CE}$OUT. A 2ns (typ) propagation delay from $\overline{CE}$IN to $\overline{CE}$OUT allows these devices to be used with most µPs and high-speed DSPs.

When $\overline{RESET}$ is deasserted, $\overline{CE}$IN is connected to $\overline{CE}$OUT through a low on-resistance transmission gate. If $\overline{CE}$IN is high when $\overline{RESET}$ is asserted, $\overline{CE}$OUT remains high regardless of any subsequent transitions on $\overline{CE}$IN during the reset event.

If $\overline{CE}$IN is low when $\overline{RESET}$ is asserted, $\overline{CE}$OUT is held low for 1µs to allow completion of the read/write operation (Figure 1). After the 1µs delay expires, $\overline{CE}$OUT goes high and stays high regardless of any subsequent transitions on $\overline{CE}$IN during the reset event. When $\overline{CE}$OUT is disconnected from $\overline{CE}$IN, $\overline{CE}$OUT is actively pulled up to OUT.

The propagation delay through the chip-enable circuitry depends on both the source impedance of the drive to $\overline{CE}$IN and the capacitive loading at $\overline{CE}$OUT. The chip-enable propagation delay is specified from the 50% point of $\overline{CE}$IN to the 50% point of $\overline{CE}$OUT, using a 50Ω driver and 50pF load capacitance. Minimize the capacitive load at $\overline{CE}$OUT and use a low output-impedance driver to minimize propagation delay.

In high-impedance mode, the leakage current at $\overline{CE}$IN is ±1µA (max) over temperature. In low-impedance mode, the impedance of $\overline{CE}$IN appears as a 75Ω resistor in series with the load at $\overline{CE}$OUT.

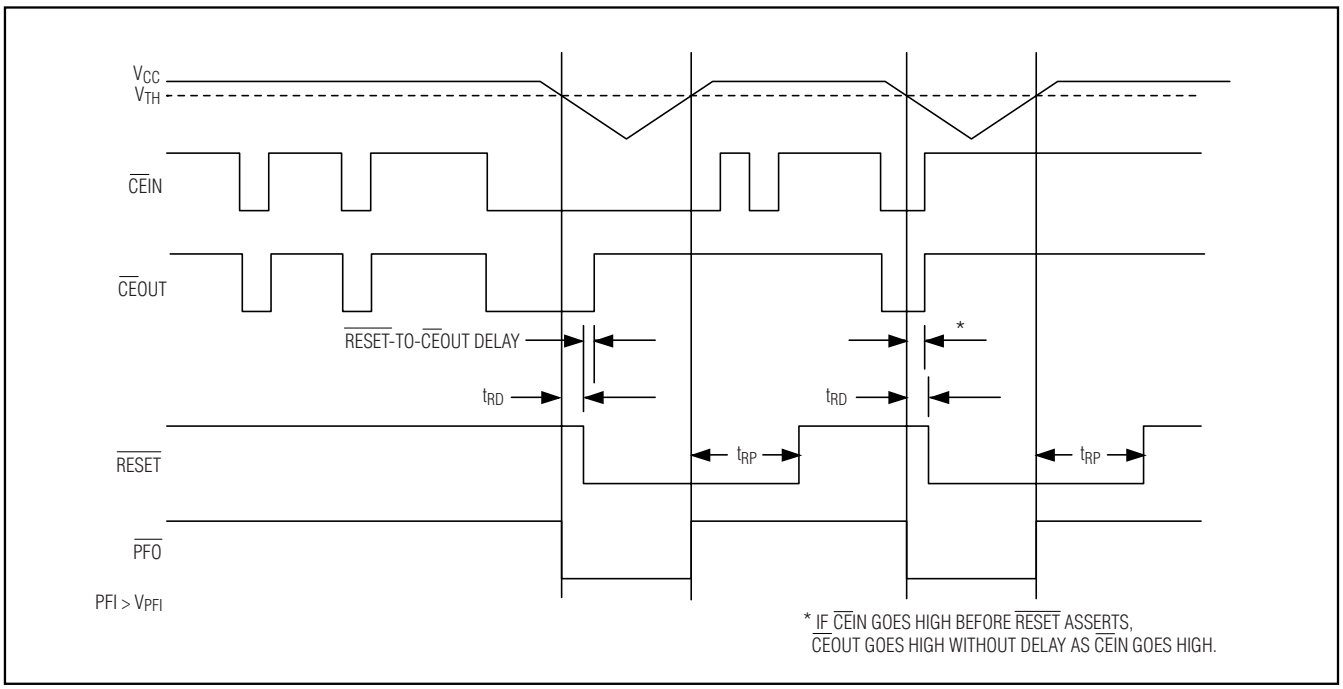


Figure 1. $\overline{RESET}$ and Chip-Enable Timing

Low-Power Battery Backup Circuits in Small µDFN Packages

Backup Battery Switchover

To preserve the contents of the RAM in a brownout or power failure, the MAX16033–MAX16040 automatically switch to back up the battery installed at BATT when the following two conditions are met:

1) V_{CC} falls below the reset threshold voltage.

2) V_{CC} is below V_{BATT}.

Table 1 lists the status of the inputs and outputs in battery-backup mode. The devices do not power-up if the only voltage source is V_{BATT}. OUT only powers up from V_{CC} at startup.

Table 1. Input and Output Status in Battery-Backup Mode

PIN	STATUS
V_{CC}	Disconnected from OUT
OUT	Connected to BATT
BATT	Connected to OUT. Current drawn from the battery is less than 1µA (at V_{BATT} = 2.8V, excluding I_{OUT}) when V_{CC} = 0V.
$\overline{RESET}$	Asserted
BATTON	High state
$\overline{MR}$, RESETIN, $\overline{CE}$IN, and WDI	Inputs ignored
$\overline{CE}$OUT	Connected to OUT
$\overline{PFO}$	Asserted

Manual-Reset Input (MAX16033/MAX16037 Only)

Many µP-based products require manual-reset capability, allowing the user or external logic circuitry to initiate a reset. For the MAX16033/MAX16037, a logic-low on $\overline{MR}$ asserts $\overline{RESET}$. $\overline{RESET}$ remains asserted while $\overline{MR}$ is low and for a minimum of 140ms (t_{RP}) after it returns high. $\overline{MR}$ has an internal 20kΩ (min) pullup resistor to V_{CC}. This input can be driven from TTL/CMOS logic outputs or with open-drain/collector outputs. Connect a normally-open momentary switch from $\overline{MR}$ to GND to create a manual-reset function; external debounce circuitry is not required. When driving $\overline{MR}$ from long cables or when using the device in a noisy environment, connect a 0.1µF capacitor from $\overline{MR}$ to GND to provide additional noise immunity.

Watchdog Input (MAX16034/MAX16038 Only)

The watchdog monitors µP activity through the watchdog input (WDI). $\overline{RESET}$ asserts when the µP fails to toggle WDI. Connect WDI to a bus line or µP I/O line. A change of state (high to low, low to high, or a minimum 100ns pulse) resets the watchdog timer. If WDI remains high or low for longer than the watchdog timeout period (t_{WD}), the internal watchdog timer runs out and triggers a reset pulse for the reset timeout period (t_{RP}). The internal watchdog timer clears whenever reset is asserted or whenever WDI sees a rising or falling edge. If WDI remains in either a high or low state, a reset pulse periodically asserts after every watchdog timeout period (t_{WD}); see Figure 2.

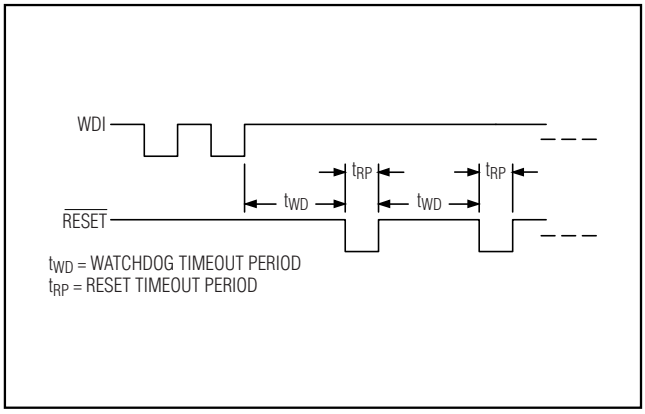


Figure 2. MAX16034/MAX16038 Watchdog Timeout Period and Reset Active Time

BATTON Indicator (MAX16035/MAX16039 Only)

BATTON is a push-pull output that asserts high when in battery-backup mode. BATTON typically sinks 3.2mA at a 0.4V saturation voltage. In battery-backup mode, this terminal sources approximately 10µA from OUT. Use BATTON to indicate battery-switchover status or to supply base drive to an external pass transistor for higher current applications (see Figure 3).

RESETIN Comparator (MAX16036/MAX16040 Only)

An internal 1.235V reference sets the RESETIN threshold voltage. $\overline{RESET}$ asserts when the voltage at RESETIN is below 1.235V. Use the RESETIN function to monitor a secondary power supply.

Use the following equations to set the reset threshold voltage (V_{RTH}) of the secondary power supply (see Figure 4):

$$V_{RTH} = V_{REF} (R1 / R2 + 1)$$

where V_{REF} = 1.235V. To simplify the resistor selection, choose a value for R2 and calculate R1.

$$R1 = R2 [(V_{RTH} / V_{REF}) - 1]$$

Since the input current at RESETIN is 25nA (max), large values (up to 1MΩ) can be used for R2 with no significant loss in accuracy.

Power-Fail Comparator

The MAX16033–MAX16040 issue an interrupt (nonmaskable or regular) to the µP when a power failure occurs. The power line is monitored by two external resistors connected to the power-fail input (PFI). When the voltage at PFI falls below 1.235V, the power-fail output ($\overline{PFO}$) drives the processor's NMI input low. An earlier power-fail warning can be generated if the unregulated DC input of the regulator is available for monitoring. The MAX16033–MAX16040 turn off the power-fail comparator and force $\overline{PFO}$ low when V_{CC} falls below the reset threshold voltage (see Figure 1). The MAX160_ _L devices provide push-pull $\overline{PFO}$ outputs. The MAX160_ _P devices provide open-drain $\overline{PFO}$ outputs.

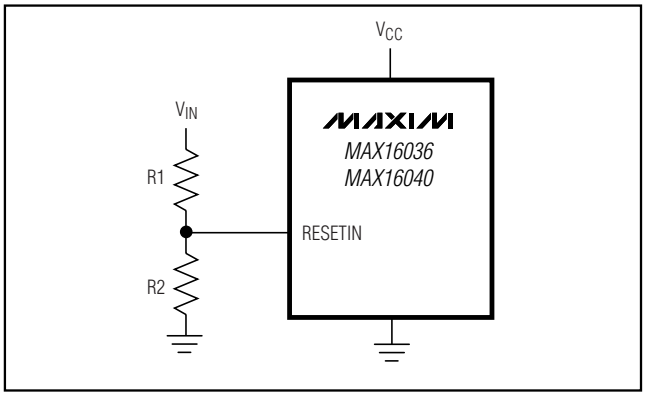


Figure 4. Setting RESETIN Voltage for the MAX16036/MAX16040

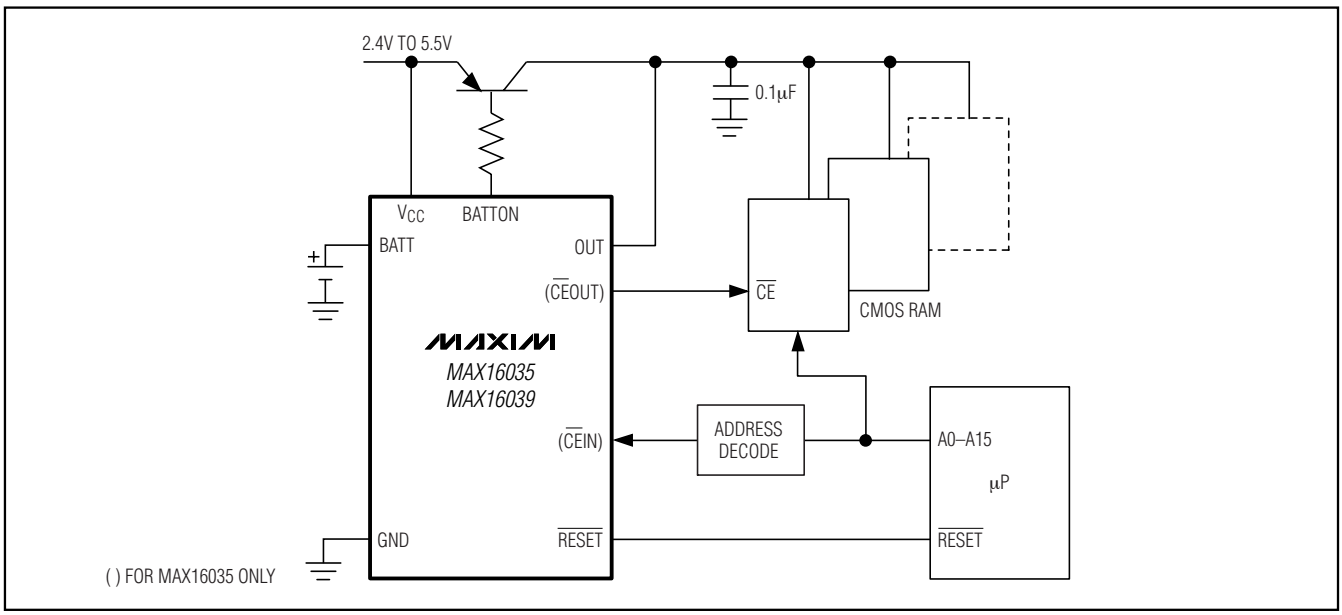


Figure 3. MAX16035/MAX16039 BATTON Driving an External Pass Transistor

Low-Power Battery Backup Circuits in Small µDFN Packages

RESET

A µP's reset input puts the µP in a known state. The MAX16033–MAX16040 µP supervisory circuits assert a reset to prevent code-execution errors during power-up, power-down, and brownout conditions. RESET asserts when V_{CC} is below the reset threshold voltage and for at least 140ms (t_{RP}) after V_{CC} rises above the reset threshold. RESET also asserts when MR is low (MAX16033/MAX16037) or when RESETIN is below 1.235V (MAX16036/MAX16040). The MAX16034/MAX16038 watchdog function causes RESET to assert in pulses following a watchdog timeout (Figure 2). The MAX160_ _L devices provide push-pull RESET outputs. The MAX160_ _P devices provide open-drain RESET outputs.

Applications Information

Operation Without a Backup Power Source

The MAX16033–MAX16040 provide a battery backup function. If a backup power source is not used, connect BATT to GND and OUT to V_{CC}.

Using a Super Cap as a Backup Power Source

Super caps are capacitors with extremely high capacitance, such as 0.47F. Figure 5 shows two methods to use a super cap as a backup power source. Connect the super cap through a diode to the 3V input (Figure 5a) or connect the super cap through a diode to 5V (Figure 5b) if a 5V supply is available. The 5V supply charges the super cap to a voltage close to 5V, allowing a longer backup period. Since V_{BATT} can be higher than V_{CC} while V_{CC} is above the reset threshold voltage, there are no special precautions required when using these µP supervisors with a super cap.

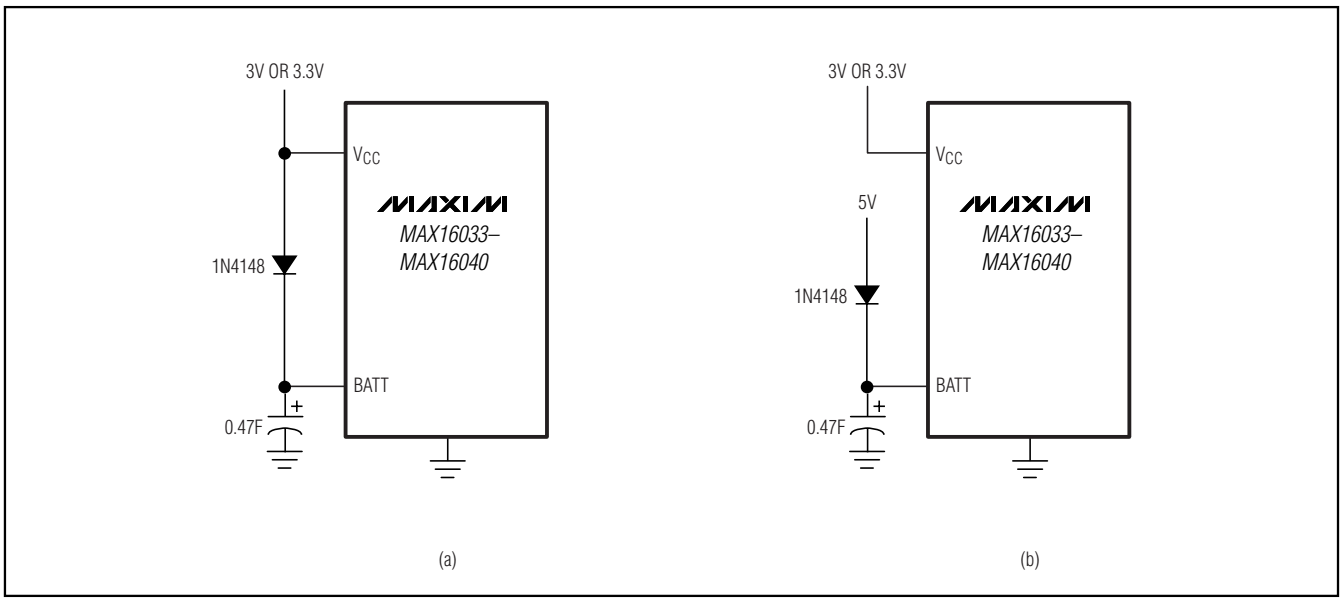


Figure 5. Using a Super Cap as a Backup Source

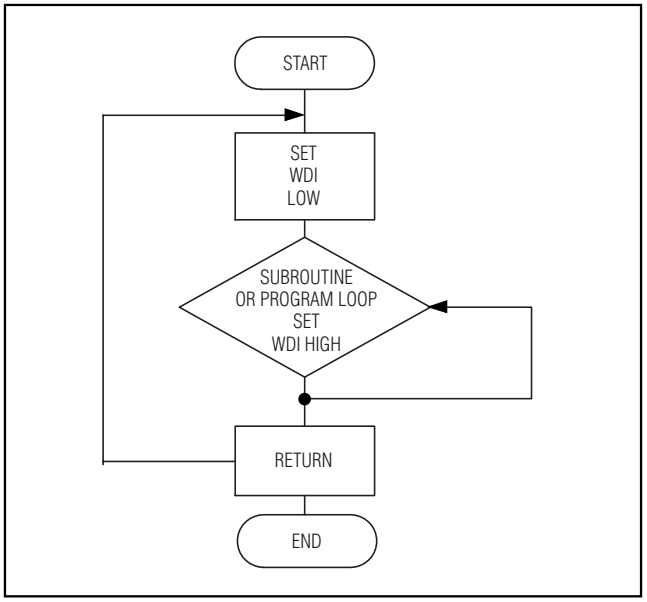


Figure 6. Watchdog Flow Diagram

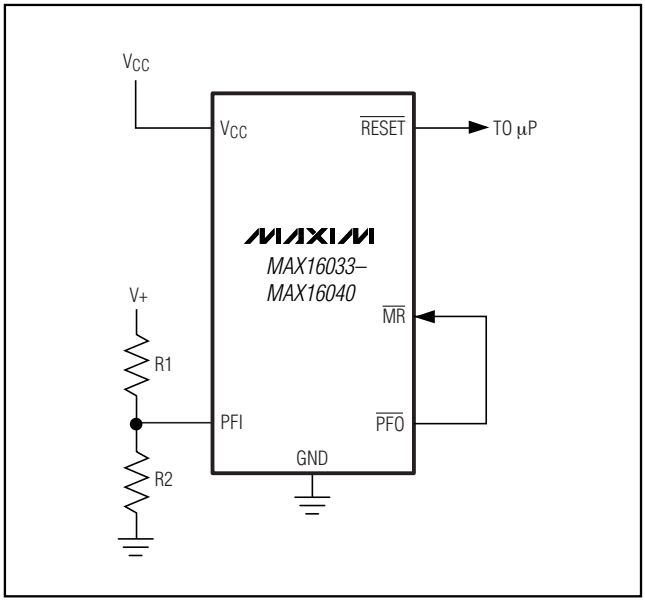


Figure 7. Monitoring an Additional Power Supply

Watchdog Software Considerations

One way to help the watchdog timer to monitor software execution more closely is to set and reset the watchdog at different points in the program, rather than pulsing the watchdog input periodically. Figure 6 shows a flow diagram where the I/O driving the watchdog is set low in the beginning of the program, set high at the beginning of every subroutine or loop, and set low again when the program returns to the beginning. If the program should hang in any subroutine, the watchdog would timeout and reset the µP.

Replacing the Backup Battery

Decouple BATT to GND with a 0.1µF capacitor. The backup power source may be removed while V_{CC} remains valid without the danger of triggering a reset pulse. The device does not enter battery-backup mode when V_{CC} stays above the reset threshold voltage.

Power-Fail Comparator

Monitoring an Additional Power Supply

Monitor another voltage by connecting a resistive divider to PFI as shown in Figure 7. The threshold voltage is:

$$V_{TH(PFI)} = 1.235\ (R1 / R2 + 1)$$

where $V_{TH(PFI)}$ is the threshold at which the monitored voltage will trip $\overline{PFO}$.

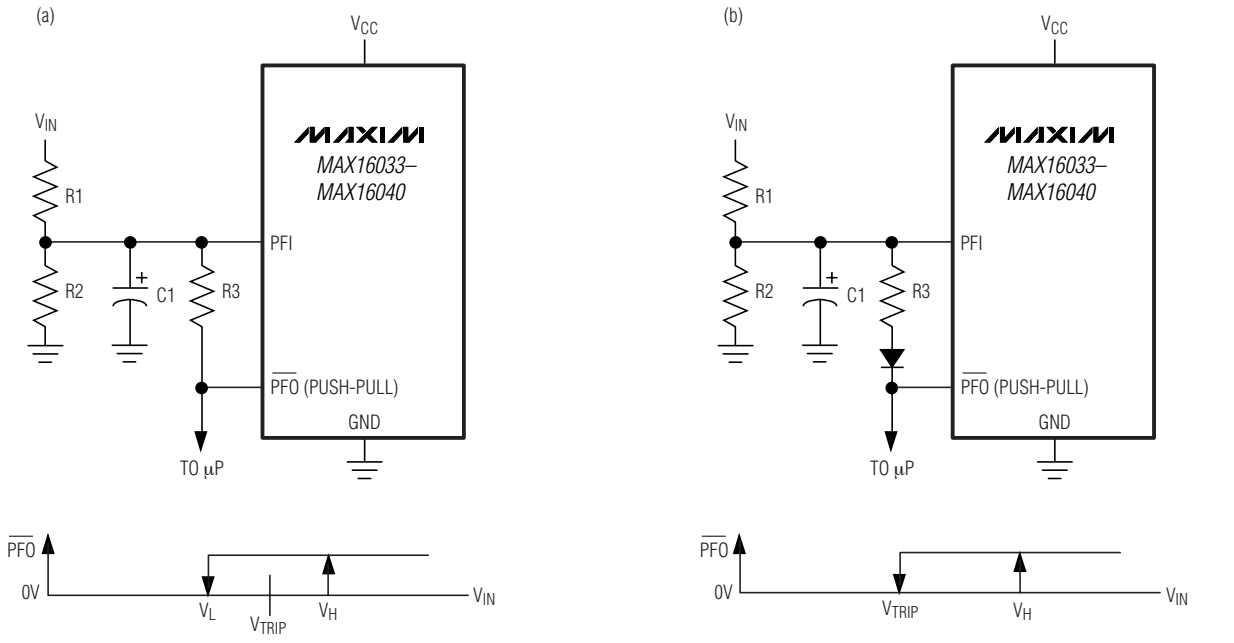
To simplify the resistor selection, choose a value for R2 and calculate R1.

$$R1 = R2\ [(V_{TH(PFI)} / 1.235) - 1]$$

Connect $\overline{PFO}$ to $\overline{MR}$ in applications that require $\overline{RESET}$ to assert when the second voltage falls below its threshold. $\overline{RESET}$ remains asserted as long as $\overline{PFO}$ holds $\overline{MR}$ low, and for 140ms (min) after $\overline{PFO}$ goes high.

Adding Hysteresis to the Power-Fail Comparator

The power-fail comparator provides a typical hysteresis of 12mV, which is sufficient for most applications where a power-supply line is being monitored through an external voltage-divider. Connect a voltage-divider between PFI and $\overline{PFO}$ as shown in Figure 8a to provide additional noise immunity. Select the ratio of R1 and R2 such that V_{PFI} falls to 1.235V when V_{IN} drops to its trip point, V_{TRIP}. R3 adds hysteresis and is typically more than 10 times the value of R1 or R2. The hysteresis window extends above (V_H) and below (V_L) the original trip point, V_{TRIP}. Connecting an ordinary signal diode in series with R3 as shown in Figure 8b causes the lower trip point (V_L) to coincide with the trip point without hysteresis (V_{TRIP}). This method provides additional noise margin without compromising the accuracy of the power-fail threshold when the monitored voltage is falling. Set the current through R1 and R2 to be at least 10µA to ensure that the 100nA (max) PFI input current does not shift the trip point. Set R3 to be higher than 10kΩ to reduce the load at $\overline{PFO}$. Capacitor C1 adds additional noise rejection.



$$V_{TRIP} = V_{PFT}\left(1 + \frac{R1}{R2}\right)$$

$$V_H = (V_{PFT} + V_{PFH})\left(1 + \frac{R1}{R2} + \frac{R1}{R3}\right)$$

$$V_L = V_{PFT}\left(1 + \frac{R1}{R2} + \frac{R1}{R3}\right) - \frac{R1}{R3} V_{CC}$$

$V_{PFT} = 1.235V$

$V_{PFH} = 12mV$

$$V_{TRIP} = V_{PFT}\left(1 + \frac{R1}{R2}\right)$$

$$V_H = (V_{PFT} + V_{PFH})\left(1 + \frac{R1}{R2} + \frac{R1}{R3}\right) - \frac{R1}{R3} V_D$$

$V_L = V_{TRIP}$

$V_{PFT} = 1.235V$

$V_{PFH} = 12mV$

V_D = DIODE FORWARD VOLTAGE

Figure 8. (a) Adding Additional Hysteresis to the Power-Fail Comparator. (b) Shifting the Additional Hysteresis above V_{TRIP}

Monitoring a Negative Voltage

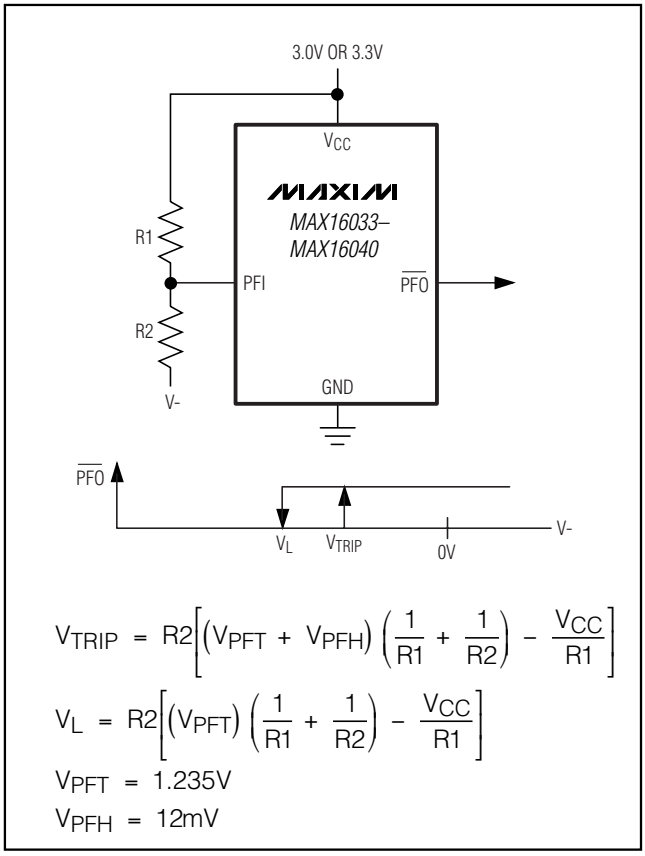
Connect the circuit as shown in Figure 9 to use the power-fail comparator to monitor a negative supply rail. $\overline{PFO}$ stays low when V- is good. When V- rises to cause PFI to be above +1.235V, $\overline{PFO}$ goes high. Ensure V_{CC} comes up before the negative supply.

Negative-Going V_{CC} Transients

The MAX16033–MAX16040 are relatively immune to short-duration, negative-going V_{CC} transients. Resetting the µP when V_{CC} experiences only small glitches is not usually desired.

The *Typical Operating Characteristics* section contains a Maximum Transient Duration vs. Reset Threshold Overdrive graph. The graph shows the maximum pulse width of a negative-going V_{CC} transient that would not trigger a reset pulse. As the amplitude of the transient increases (i.e., goes further below the reset threshold voltage), the maximum allowable pulse width decreases. Typically, a V_{CC} transient that goes 100mV below the reset threshold and lasts for 25µs does not trigger a reset pulse.

A 0.1µF bypass capacitor mounted close to V_{CC} provides additional transient immunity.



$$V_{TRIP} = R2\left[\left(V_{PFT} + V_{PFH}\right)\left(\frac{1}{R1} + \frac{1}{R2}\right) - \frac{V_{CC}}{R1}\right]$$

$$V_L = R2\left[\left(V_{PFT}\right)\left(\frac{1}{R1} + \frac{1}{R2}\right) - \frac{V_{CC}}{R1}\right]$$

$V_{PFT} = 1.235V$

$V_{PFH} = 12mV$

Figure 9. Monitoring a Negative Voltage

Low-Power Battery Backup Circuits in Small µDFN Packages

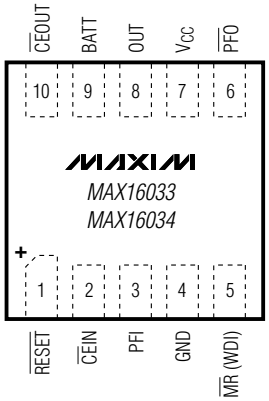
Device Marking Codes

PART	TOP MARK	PART	TOP MARK	PART	TOP MARK	PART	TOP MARK
MAX16033LLB23+T	+ABE	MAX16035LLB23+T	+ACC	MAX16037LLA23+T	+ABX	MAX16039LLA23+T	+ACV
MAX16033LLB26+T	+ABF	MAX16035LLB26+T	+ACD	MAX16037LLA26+T	+ABY	MAX16039LLA26+T	+ACW
MAX16033LLB29+T	**+ABG**	**MAX16035LLB29+**	**+ACE**	**MAX16037LLA29+**	**+ABZ**	**MAX16039LLA29+T**	**+ACX**
MAX16033LLB31+T	**+ABH**	**MAX16035LLB31+**	**+ACF**	**MAX16037LLA31+**	**+ACA**	**MAX16039LLA31+T**	**+ACY**
MAX16033LLB44+T	+ABI	MAX16035LLB44+T	+ACG	MAX16037LLA44+T	+ACB	MAX16039LLA44+T	+ACZ
MAX16033LLB46+T	**+ABJ**	**MAX16035LLB46+**	**+ACH**	**MAX16037LLA46+**	**+ACC**	**MAX16039LLA46+T**	**+ADA**
MAX16033PLB23+T	+ABK	MAX16035PLB23+T	+ACI	MAX16037PLA23+T	+ACD	MAX16039PLA23+T	+ADB
MAX16033PLB26+T	+ABL	MAX16035PLB26+T	+ACJ	MAX16037PLA26+T	+ACE	MAX16039PLA26+T	+ADC
MAX16033PLB29+	**+ABM**	**MAX16035PLB29+**	**+ACK**	**MAX16037PLA29+**	**+ACF**	**MAX16039PLA29+**	**+ADD**
MAX16033PLB31+	**+ABN**	**MAX16035PLB31+**	**+ACL**	**MAX16037PLA31+**	**+ACG**	**MAX16039PLA31+**	**+ADE**
MAX16033PLB44+T	+ABO	MAX16035PLB44+T	+ACM	MAX16037PLA44+T	+ACH	MAX16039PLA44+T	+ADF
MAX16033PLB46+	**+ABP**	**MAX16035PLB46+**	**+ACN**	**MAX16037PLA46+**	**+ACI**	**MAX16039PLA46+**	**+ADG**
MAX16034LLB23+T	+ABQ	MAX16036LLB23+T	+ACO	MAX16038LLA23+T	+ACJ	MAX16040LLA23+T	+ADH
MAX16034LLB26+T	+ABR	MAX16036LLB26+T	+ACP	MAX16038LLA26+T	+ACK	MAX16040LLA26+T	+ADI
MAX16034LLB29+T	**+ABS**	**MAX16036LLB29+**	**+ACQ**	**MAX16038LLA29+**	**+ACL**	**MAX16040LLA29+T**	**+ADJ**
MAX16034LLB31+T	**+ABT**	**MAX16036LLB31+**	**+ACR**	**MAX16038LLA31+**	**+ACM**	**MAX16040LLA31+T**	**+ADK**
MAX16034LLB44+T	+ABU	MAX16036LLB44+T	+ACS	MAX16038LLA44+T	+ACN	MAX16040LLA44+T	+ADL
MAX16034LLB46+T	**+ABV**	**MAX16036LLB46+**	**+ACT**	**MAX16038LLA46+**	**+ACO**	**MAX16040LLA46+T**	**+ADM**
MAX16034PLB23+T	+ABW	MAX16036PLB23+T	+ACU	MAX16038PLA23+T	+ACP	MAX16040PLA23+T	+ADN
MAX16034PLB26+T	+ABX	MAX16036PLB26+T	+ACV	MAX16038PLA26+T	+ACQ	MAX16040PLA26+T	+ADO
MAX16034PLB29+	**+ABY**	**MAX16036PLB29+**	**+ACW**	**MAX16038PLA29+**	**+ACR**	**MAX16040PLA29+**	**+ADP**
MAX16034PLB31+	**ABZ**	**MAX16036PLB31+**	**+ACX**	**MAX16038PLA31+**	**+ACS**	**MAX16040PAL31+**	**+ADQ**
MAX16034PLB44+T	+ACA	MAX16036PLB44+T	+ACY	MAX16038PLA44+T	+ACT	MAX16040PLA44+T	+ADR
MAX16034PLB46+	**+ACB**	**MAX16036PLB46+**	**+ACZ**	**MAX16038PLA46+**	**+ACU**	**MAX16040PLA46+**	**+ADS**

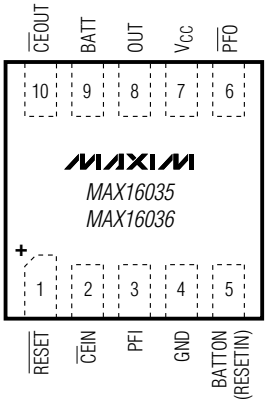
Note: *48 standard versions shown in bold are available. Sample stock is generally held on standard versions only. Contact factory for nonstandard versions availability.*

Pin Configurations

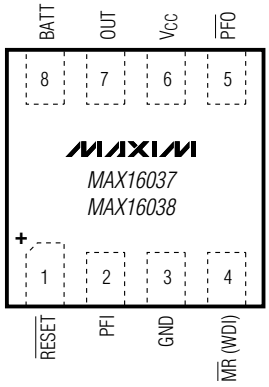
TOP VIEW



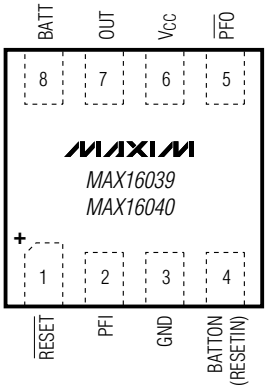
10-µDFN
( ) FOR MAX16034 ONLY



10-µDFN
( ) FOR MAX16036 ONLY



8-µDFN
( ) FOR MAX16038 ONLY

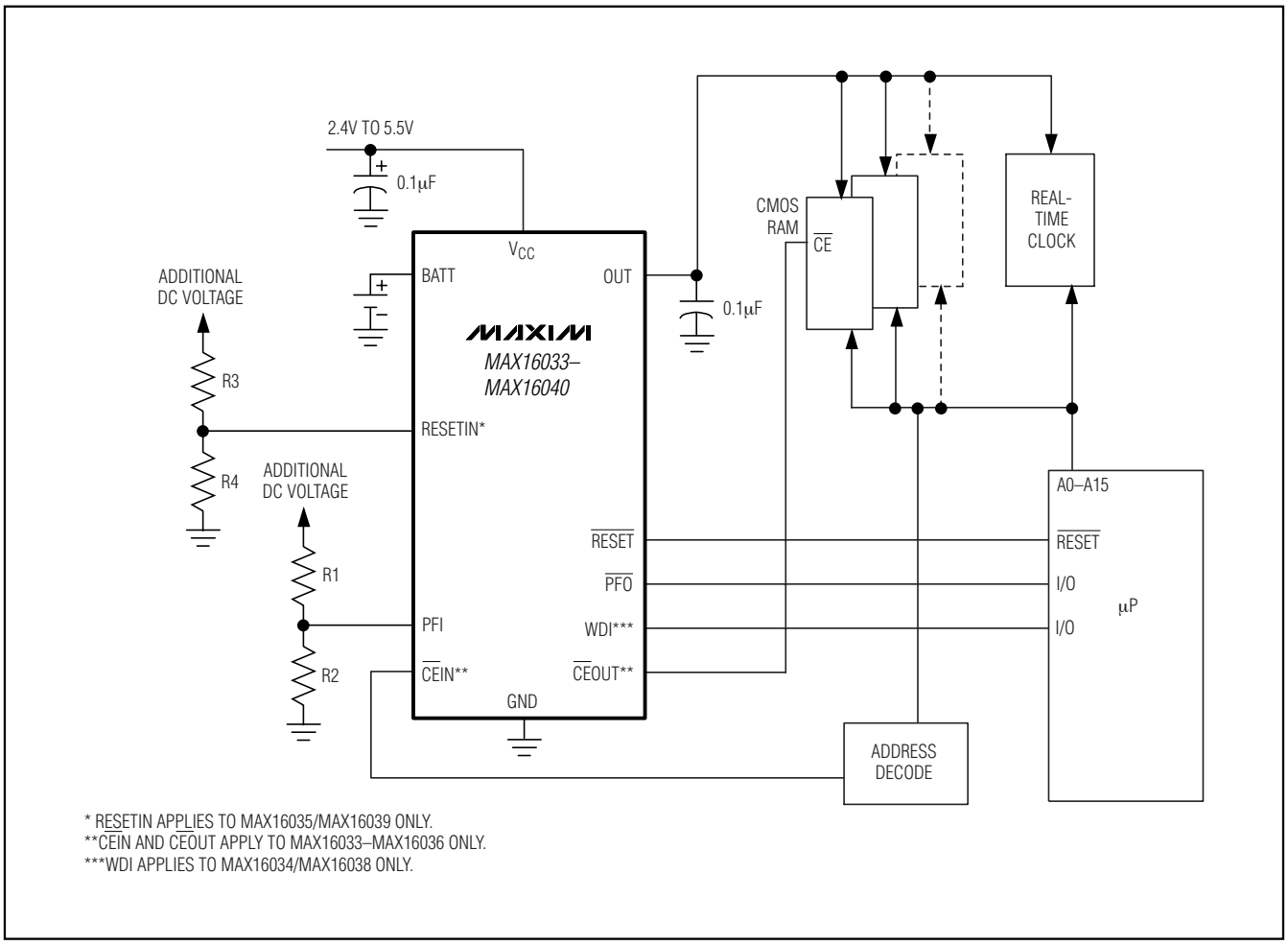


8-µDFN
( ) FOR MAX16040 ONLY

+ DENOTES A LEAD-FREE PACKAGE.

Low-Power Battery Backup Circuits in Small µDFN Packages

Typical Operating Circuit



Ordering Information (continued)

PART*	TEMP RANGE	PIN-PACKAGE	PKG CODE
MAX16035LLB_ _+T	-40°C to +85°C	10 µDFN-10	L1022-1
MAX16035PLB_ _+T	-40°C to +85°C	10 µDFN-10	L1022-1
MAX16036LLB_ _+T	-40°C to +85°C	10 µDFN-10	L1022-1
MAX16036PLB_ _+T	-40°C to +85°C	10 µDFN-10	L1022-1
MAX16037LLA_ _+T	-40°C to +85°C	8 µDFN-8	L822-1
MAX16037PLA_ _+T	-40°C to +85°C	8 µDFN-8	L822-1
MAX16038LLA_ _+T	-40°C to +85°C	8 µDFN-8	L822-1
MAX16038PLA_ _+T	-40°C to +85°C	8 µDFN-8	L822-1
MAX16039LLA_ _+T	-40°C to +85°C	8 µDFN-8	L822-1
MAX16039PLA_ _+T	-40°C to +85°C	8 µDFN-8	L822-1
MAX16040LLA_ _+T	-40°C to +85°C	8 µDFN-8	L822-1
MAX16040PLA_ _+T	-40°C to +85°C	8 µDFN-8	L822-1

**These parts offer a choice of reset threshold voltages. From the Reset Threshold Ranges table, insert the desired threshold voltage code in the blank to complete the part number. See Selector Guide for a listing of device features.*
+Denotes a lead-free package.
T = *Tape and reel.*

Reset Threshold Ranges

SUFFIX	RESET THRESHOLD VOLTAGE (V)		
	MIN	TYP	MAX
46	4.50	4.63	4.75
44	4.25	4.38	4.50
31	3.00	3.08	3.15
29	2.85	2.93	3.00
26	2.55	2.63	2.70
23	2.25	2.32	2.38

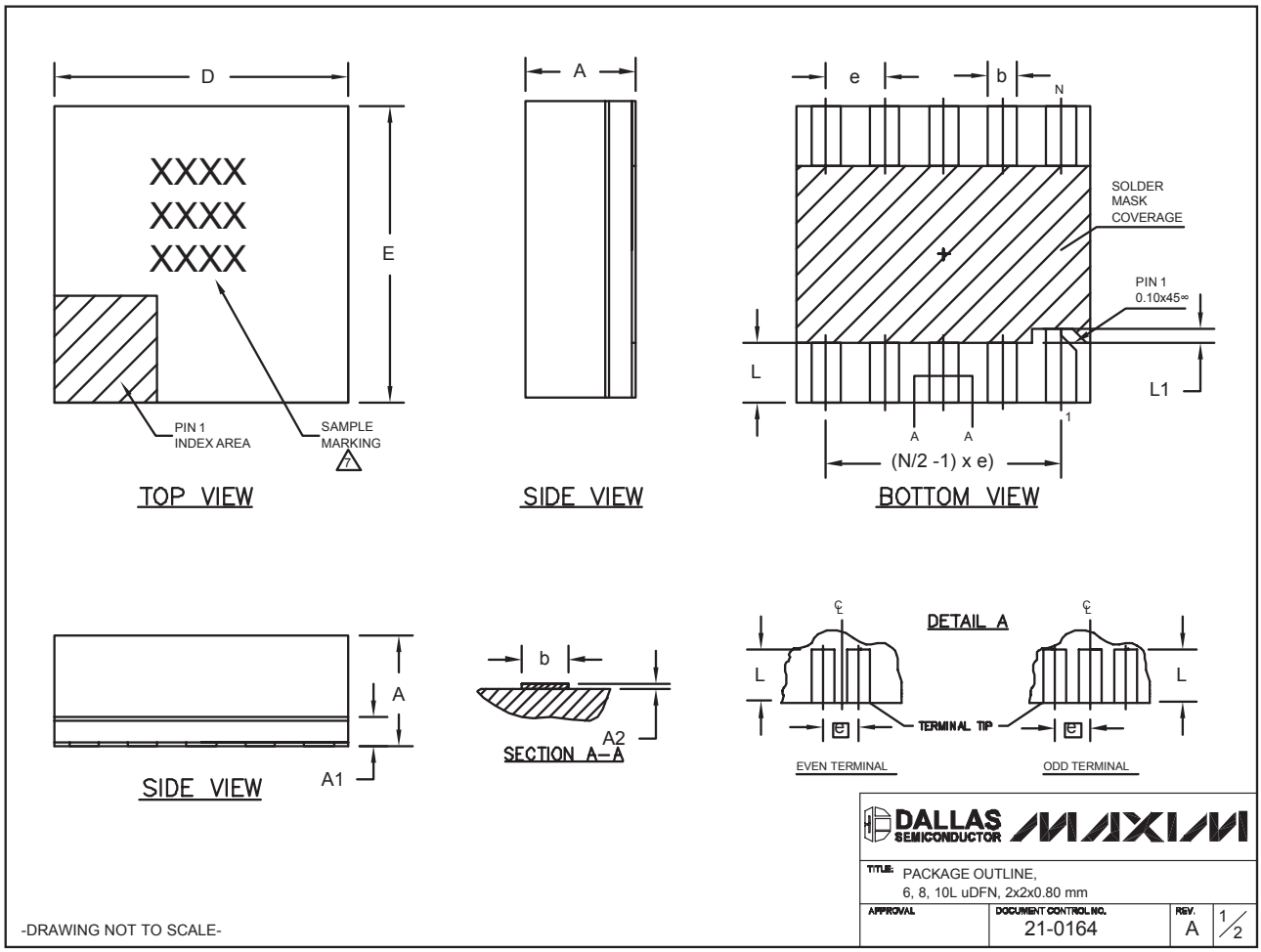
Chip Information

PROCESS: BiCMOS

Low-Power Battery Backup Circuits in Small µDFN Packages

Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)



Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)

COMMON DIMENSIONS			
SYMBOL	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
A1	0.15	0.20	0.25
A2	0.020	0.025	0.035
D	1.95	2.00	2.05
E	1.95	2.00	2.05
L	0.30	0.40	0.50
L1	0.10 REF.		

PACKAGE VARIATIONS				
PKG. CODE	N	e	b	(N/2 -1) x e
L622-1	6	0.65 BSC	0.30±0.05	1.30 REF.
L822-1	8	0.50 BSC	0.25±0.05	1.50 REF.
L1022-1	10	0.40 BSC	0.20±0.03	1.60 REF.

NOTES:
1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY SHALL NOT EXCEED 0.08mm.
3. WARPAGE SHALL NOT EXCEED 0.10mm.
4. PACKAGE LENGTH/PACKAGE WIDTH ARE CONSIDERED AS SPECIAL CHARACTERISTIC(S).
5. "N" IS THE TOTAL NUMBER OF LEADS.
6. NUMBER OF LEADS SHOWN ARE FOR REFERENCE ONLY.
7. MARKING IS FOR PACKAGE ORIENTATION REFERENCE ONLY.

-DRAWING NOT TO SCALE-

DALLAS SEMICONDUCTOR MAXIM

TITLE: PACKAGE OUTLINE, 6, 8, 10L uDFN, 2x2x0.80 mm

APPROVAL	DOCUMENT CONTROL NO.	REV.	
	21-0164	A	2/2